SSAJ 0.7(H)mm, 1.4mm-travel Surface Mount Type

Compact type with 0.7mm body height

Typical Specifications

Items		Specifications
Rating (max.)/(min.) (Resistive load)		10mA 5V DC / 50μA 3V DC
Contact resistance (Initial performance / After lifetime)		300mΩ max. / 500mΩ max.
Operating force		1.5±1N
Operating life	Without load	10,000 cycles
	With load	10,000 cycles (10mA 5V DC)

Product Line

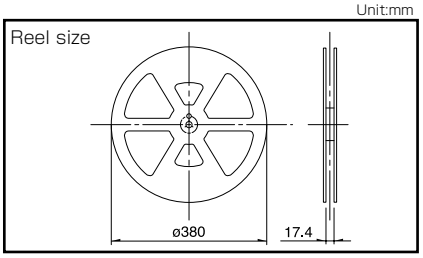
Travel (mm)	Operating section directions	Poles	Positions	Changeover timing	Soldering	Location lug	Minimum order unit (pcs.) Japan	Minimum order unit (pcs.) Export	Products No.	Drawing No.
1.4	Horizontal	1	2	Not specified	Reflow	With	5,000	20,000	**SSAJ110100**	1
						Without			**SSAJ120100**	2

Packing Specifications

Taping

Number of packages (pcs.) 1 reel	1 case /Japan	1 case /export packing	Tape width (mm)	Export package measurements (mm)
5,000	10,000	20,000	16	417×409×139

Unit:mm

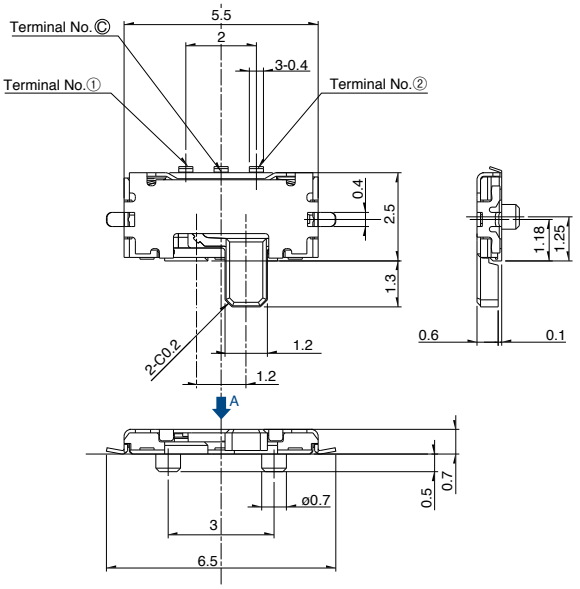
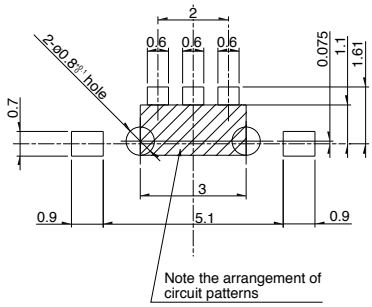
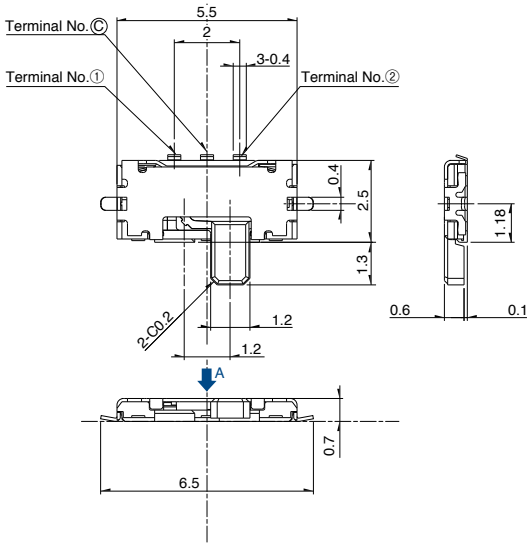
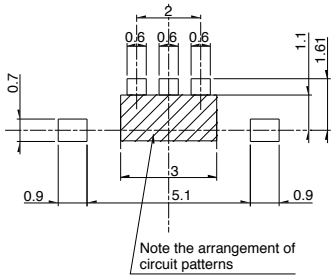


ALPSALPINE

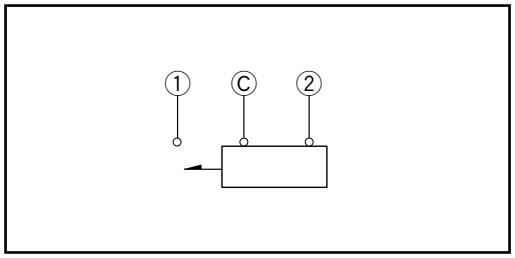
Refer to P.106 for soldering conditions.

Dimensions

Unit:mm

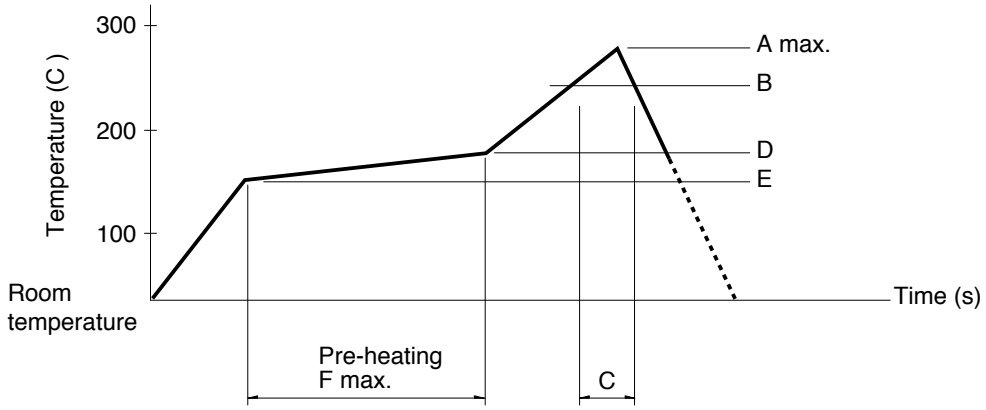
No.	Style	PC board mounting hole and land dimensions (Viewed from the direction A)
1		
2		

Circuit Diagram (Viewed from Direction A)



Example of Reflow Soldering Condition

1. Heating method: Double heating method with infrared heater.
2. Temperature measurement: Thermocouple ϕ 0.1 to 0.2 CA (K) or CC (T) at soldering portion (copper foil surface).
   A heat resisting tape should be used for fixed measurement.
3. Temperature profile



Series (Reflow type)			A (℃) 3s max.	B (℃)	C (s)	D (℃)	E (℃)	F (s)
SSSS2	Vertical	1-pole, 3-position	260	230	40	180	150	120
	Horizontal	1-pole, 2-position 1-pole, 3-position 2-pole, 3-position						
	Vertical	1-pole, 2-position	250					
SSSS7								
SSAH, SSAG, SSAJ, SSAL, SSSS8			260					

Notes

1. The condition mentioned above is the temperature on the mounting surface of a PC board. There are cases where the PC board's temperature greatly differs from that of the switch, depending on the PC board's material, size, thickness, etc. The above-stated conditions shall also apply to switch surface temperatures.
2. Soldering conditions differ depending on reflow soldering machines. Prior verification of soldering condition is highly recommended.

Reference for Hand Soldering

Series	Soldering temperature	Soldering time
SSSF, SSSU	350±10℃	3+1/0s
SSSS2	350±10℃	4s max.
SSSS9	350±10℃	3s max.
SSAH, SSAG, SSAJ, SSAL	350±5℃	3s max.
SSSS8	330±5℃	3s max.
SSSS7	320±5℃	3s max.
SSAC	300±10℃	2s max.

Reference for Dip Soldering

(For PC board terminal types)

Series	Items		Dip soldering	
	Preheating temperature	Preheating time	Soldering temperature	Duration of immersion
SSSS2	100℃ max.	60s max.	260±5℃	3±1s
SSSS9	120℃ max.	60s max.	260±5℃	5+0/-1s (2 times)
SSSF, SSSU	100℃ max.	60s max.	260±5℃	10±1s/5±1s
SSAC	100℃ max.	60s max.	260±5℃	5±1s